

SERIES 53

BOND HEADS

SMALL.
MANUAL.
EASY.

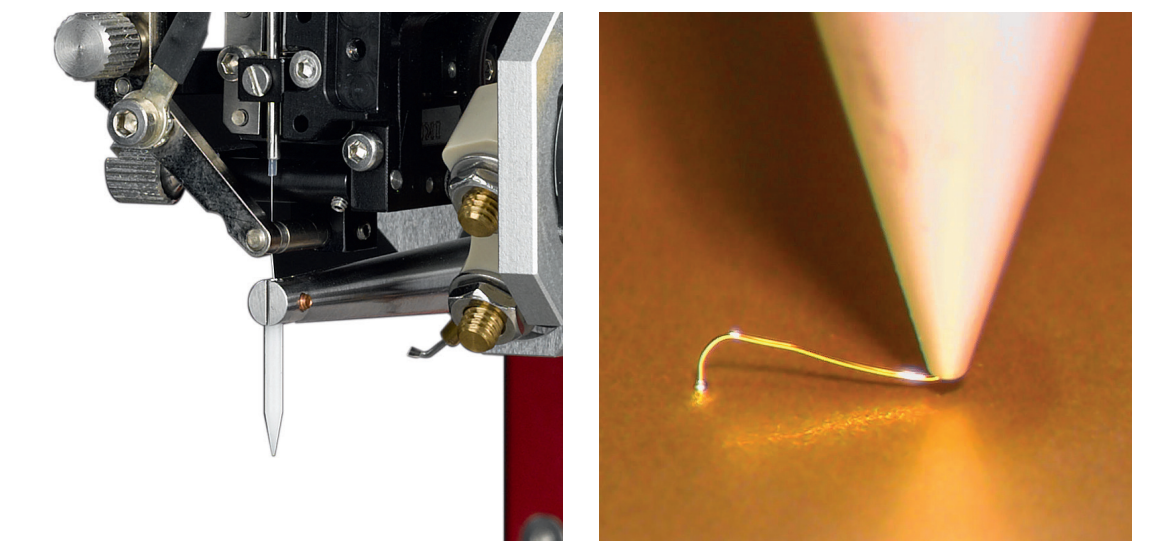


53
SERIES

FMS
BONDTEC

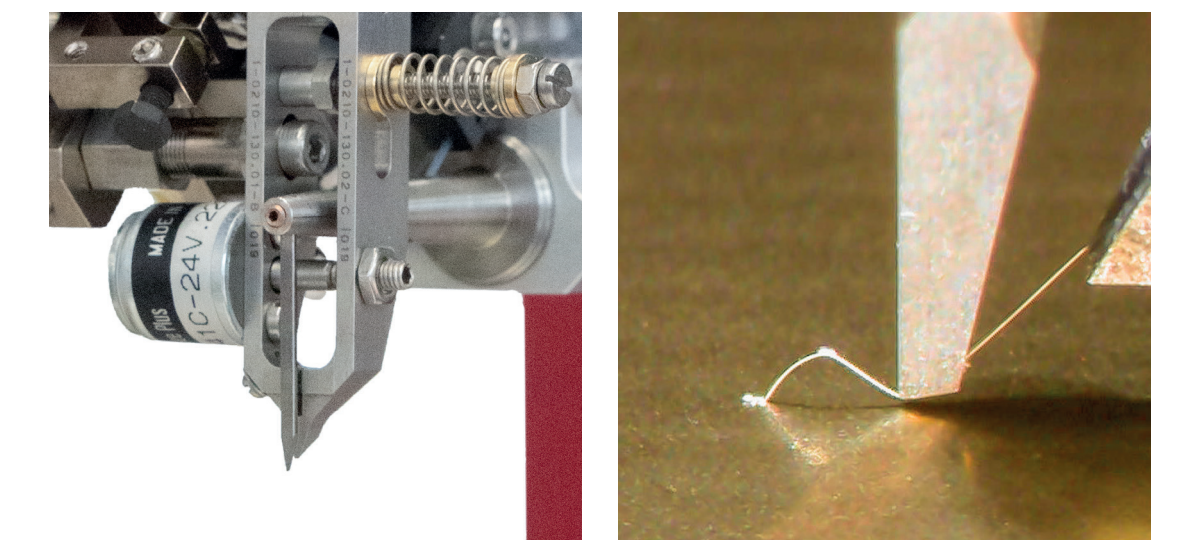
5310 – Gold Ball

- » Gold-Ball bonding for wires from 17,5 to 50 μm
- » Standard-Capillaries 16 mm to 19 mm
- » Bumping, Safety-Bump, Stitch-on-Ball



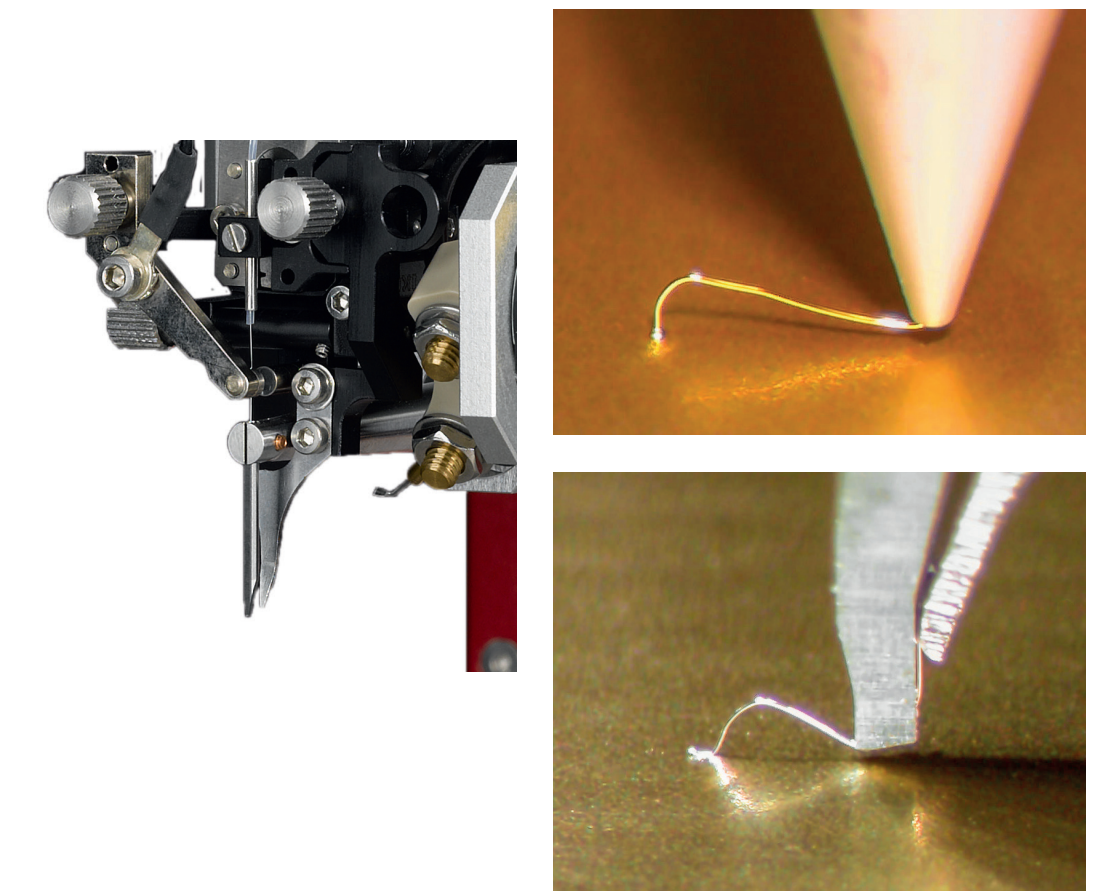
5330 – Thin Wire

- » Wedge-Wedge bonding using 1" Tools
- » Aluminum and Gold wires from 17.5 to 75 μm strength
- » 45° wire guide, retrofittable to 30° and 60°
- » Programmable Y-axis 20 mm



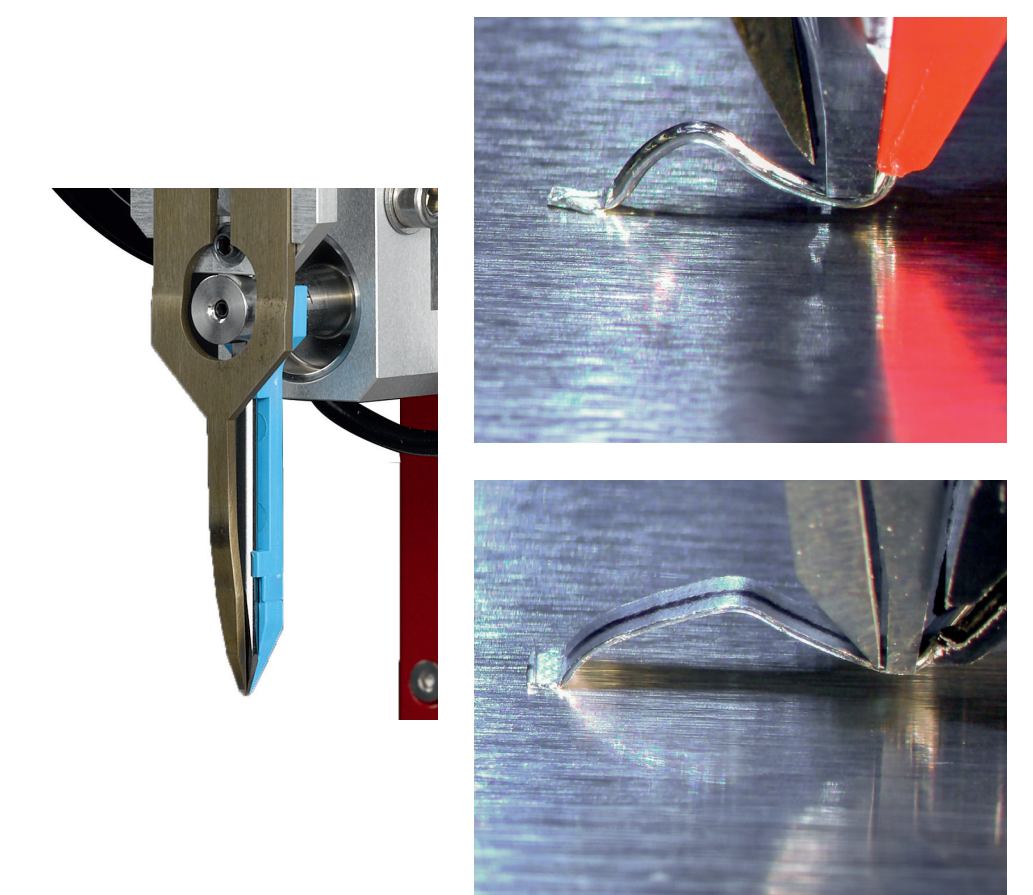
53 BDA – Ball Deep Access

- » Wedge-Wedge bonding using 1" or $\frac{3}{4}$ " Tools with 90° wire guide for Aluminum and Gold wires from 17,5 to 75 μm
- » Useable with Aluminum and Gold ribbon
- » Gold-Ball bonding for wires from 17,5 to 50 μm
- » Perfect for difficult and constricted bonding geometry
- » Programmable Y-axis 20 mm
- » **Optional: retrofittable 5380 DIE-Bonder**



5350 – Heavy Wire

- » Wedge-Wedge bonding for Aluminum and heavy wire from 100 up to 500 μm diameter // Copper from 100 up to 300 μm
- » Wedge Tool lengths from 50 to 70 mm
- » Stitch or chain bonds of any length
- » Clip-on wire guide
- » Programmable Y-axis 20 mm



5350_{HR} – Heavy Ribbon

- » Wedge-Wedge-bonding for Aluminum ribbon
- » Stitch or chain bonds of any length
- » Programmable Y-axis 20 mm
- » Bond force amplify up to 4.000 cN

